



Material Content Data Sheet



Sales Product Name		BSF134N10NJ3 G		Issued		4. September 2015		
MA#		MA001355570						
Package		MG-WDSO-N-2-2		Weight*		50.72 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.788	5.50	5.50	54969	54969
leadframe	non noble metal	copper	7440-50-8	44.951	88.62	88.62	886254	886254
leadfinish	non noble metal	nickel	7440-02-0	0.143	0.28		2812	
	noble metal	silver	7440-22-4	0.567	1.12	1.40	11185	13997
plating	non noble metal	nickel	7440-02-0	0.111	0.22	0.22	2179	2179
glue	plastics	epoxy resin	-	0.141	0.28		2783	
	noble metal	silver	7440-22-4	0.867	1.71	1.99	17094	19877
solder	non noble metal	copper	7440-50-8	0.005	0.01		103	
	noble metal	silver	7440-22-4	0.031	0.06		617	
passivation	non noble metal	tin	7440-31-5	1.006	1.98	2.05	19837	20557
	plastics	epoxy resin	-	0.110	0.22	0.22	2167	2167
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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